2SC3496, 2SC3496A

Silicon NPN triple diffusion planar type

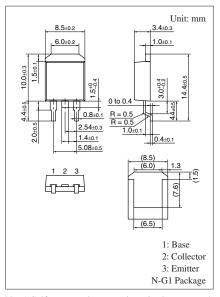
For power switching

■ Features

- High-speed switching
- ullet High collector-base voltage (Emitter open) V_{CBO}
- Satisfactory linearity of forward current transfer ratio h_{FE}
- N type package enabling direct soldering of the radiating fin to the printed circuit board, etc. of small electronic equipment

■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter	Symbol	Rating	Unit		
Collector-base voltage	2SC3496	V_{CBO}	900	V	
(Emitter open)	2SC3496A		1 000		
Collector-emitter voltage	2SC3496	V _{CES}	900	V	
(E-B short)	2SC3496A		1 000		
Collector-emitter voltage	2SC3496	V _{CEO}	800	V	
(Base open)	2SC3496A		900		
Emitter-base voltage (Coll	V_{EBO}	7	V		
Base current	I_B	0.3	A		
Collector current	I_C	1	A		
Peak collector current	I_{CP}	2	A		
Collector power	P _C	30	W		
dissipation	$T_a = 25$ °C		1.3		
Junction temperature	T _j	150	°C		
Storage temperature	T _{stg}	-55 to +150	°C		

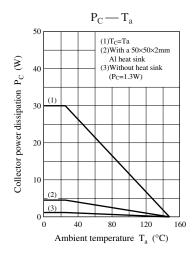


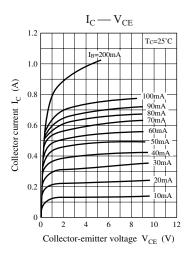
Note) Self-supported type package is also prepared.

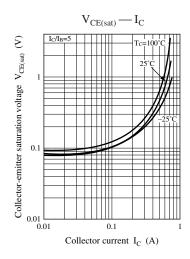
■ Electrical Characteristics $T_C = 25$ ° $C \pm 3$ °C

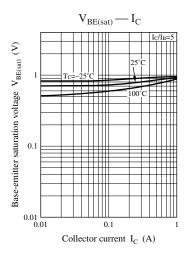
Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage	2SC3496	V_{CEO}	$I_C = 1 \text{ mA}, I_B = 0$	800			V
(Base open)	2SC3496A			900			
Collector-base cutoff current	2SC3496	I_{CBO}	$V_{CB} = 900 \text{ V}, I_{E} = 0$			50	μΑ
(Emitter open)	2SC3496A		$V_{CB} = 1000 \text{ V}, I_{E} = 0$			50	
Emitter-base cutoff current (Collector open)		I_{EBO}	$V_{EB} = 7 \text{ V}, I_{C} = 0$			50	μΑ
Forward current transfer ratio		$h_{\rm FE1}$	$V_{CE} = 5 \text{ V}, I_{C} = 0.05 \text{ A}$	6			_
		h _{FE2}	$V_{CE} = 5 \text{ V}, I_{C} = 0.5 \text{ A}$	3			
Collector-emitter saturation voltage		V _{CE(sat)}	$I_C = 0.2 \text{ A}, I_B = 0.04 \text{ A}$			1.5	V
Base-emitter saturation voltage		V _{BE(sat)}	$I_C = 0.2 \text{ A}, I_B = 0.04 \text{ A}$			1.0	V
Transition frequency		f_T	$V_{CE} = 10 \text{ V}, I_{C} = 0.05 \text{ A}, f = 1 \text{ MHz}$		4		MHz
Turn-on time		t _{on}	$I_C = 0.2 \text{ A}$			1.0	μs
Storage time		t _{stg}	$I_{B1} = 0.04 \text{ A}, I_{B2} = -0.08 \text{ A}$			3.0	μs
Fall time		$t_{\rm f}$	$V_{CC} = 250 \text{ V}$			1.0	μs

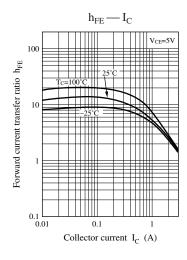
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

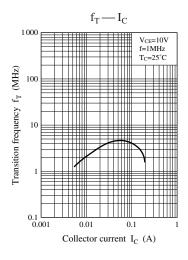


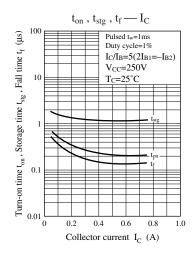


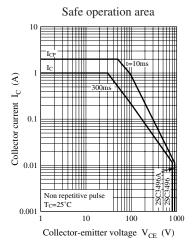




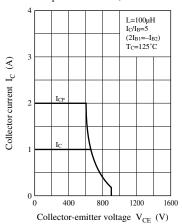




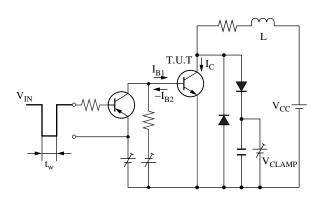


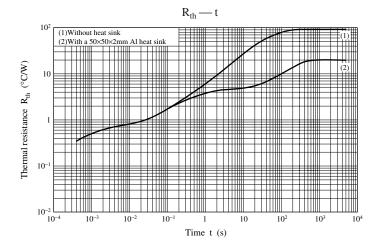


Safe operation area (Reverse bias)



Safe operation area (Reverse bias) measurement circuit





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